VTM™ Current Multiplier

VTM48EH120x010B00



High Efficiency, Sine Amplitude Converter™

FEATURES

- 48 Vdc to 12 Vdc 10 A current multiplier
  - Operating from standard 48 V or 24 V PRM modules
- High efficiency (>95%) reduces system power consumption
- High density (901 W/in³)
- "Half Chip" VI Chip® package enables surface mount, low impedance interconnect to system board
- Contains built-in protection features against:
  - Overvoltage
  - Overcurrent
  - Short Circuit
  - Overtemperature
- Provides enable/disable control, internal temperature monitoring, current monitoring
- ZVS/ZCS resonant Sine Amplitude Converter topology
- Less than 50°C temperature rise at full load in typical applications

TYPICAL APPLICATIONS

- High End Computing Systems
- Automated Test Equipment
- High Density Power Supplies
- Communications Systems

DESCRIPTION

The VI Chip current multiplier is a high efficiency (>95%) Sine Amplitude Converter™ (SAC™) operating from a 26 to 55 Vdc primary bus to deliver an isolated output. The Sine Amplitude Converter offers a low AC impedance beyond the bandwidth of most downstream regulators, which means that capacitance normally at the load can be located at the input to the Sine Amplitude Converter. Since the K factor of the VTM48EH120T010B00 is 1/4, that capacitance value can be reduced by a factor of 16, resulting in savings of board area, materials and total system cost.

The VTM48EH120T010B00 is provided in a VI Chip package compatible with standard pick-and-place and surface mount assembly processes. The co-molded VI Chip package provides enhanced thermal management due to large thermal interface area and superior thermal conductivity. With high conversion efficiency the VTM48EH120T010B00 increases overall system efficiency and lowers operating costs compared to conventional approaches.

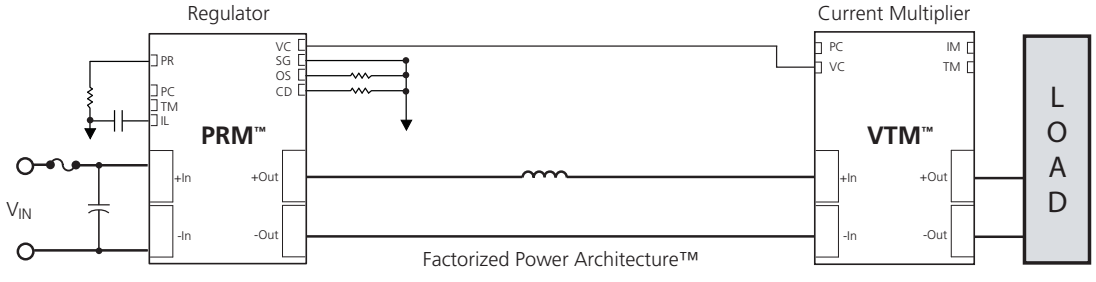
The VTM48EH120T010B00 enables the utilization of Factorized Power Architecture providing efficiency and size benefits by lowering conversion and distribution losses and promoting high density point of load conversion.

V_{IN} = 26 to 55 V	I_{OUT} = 10 A (NOM)
V_{OUT} = 6.5 to 13.8 V (NO LOAD)	K= 1/4

PART NUMBERING

PART NUMBER	PRODUCT GRADE
VTM48EH120 **x** 010B00	**T** = -40° to 125°C
	M = -55° to 125°C

For Storage and Operating Temperatures see Section 6.0 General Characteristics



(See Application Note AN:024)

1.0 ABSOLUTE MAXIMUM VOLTAGE RATINGS

The absolute maximum ratings below are stress ratings only. Operation at or beyond these maximum ratings can cause permanent damage to the device.

	MIN	MAX	UNIT
+ IN to - IN	-1.0	60	V_{DC}
PC to - IN	-0.3	20	V_{DC}
TM to -IN	-0.3	7	V_{DC}
VC to - IN	-0.3	20	V_{DC}

	MIN	MAX	UNIT
IM to - IN	0	3.15	V_{DC}
+ IN / - IN to + OUT / - OUT (hipot)		2250	V_{DC}
+ OUT to - OUT	-1.0	16	V_{DC}

2.0 ELECTRICAL CHARACTERISTICS

Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of **-40°C < T_J < 125°C (T-Grade)**; All other specifications are at **T_J = 25°C** unless otherwise noted.

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
Input Voltage Range	V_{IN}	No external VC applied	**26**		**55**	V_{DC}
		VC applied	**0**		**55**	
V_{IN} Slew Rate	dV_{IN}/dt				**1**	V/µs
V_{IN} UV Turn Off	V_{IN_UV}	Module latched shutdown, No external VC applied, I_{OUT} = 10A		19.2	**26.0**	V
No Load power dissipation	P_{NL}	V_{IN} = 48 V	**0.8**		**4.1**	W
		V_{IN} = 26 V to 55 V			**5**	
		V_{IN} = 48 V, T_C = 25°C		2.0	2.8	
		V_{IN} = 26 V to 55 V, T_C = 25°C			4	
Inrush current peak	I_{INRP}	VC enable, V_{IN} = 48 V C_{OUT} = 500 µF, R_{LOAD} = 1162 mΩ		8	**12**	A
DC input current	I_{IN_DC}				**2.7**	A
Transfer ratio	K	K = V_{OUT}/V_{IN}, I_{OUT} = 0 A		1/4		V/V
Output voltage	V_{OUT}	$V_{OUT} = V_{IN} \cdot K - I_{OUT} \cdot R_{OUT}$, Section 11				V
Output current (average)	I_{OUT_AVG}				**10**	A
Output current (peak)	I_{OUT_PK}	T_{PEAK} < 10 ms, $I_{OUT_AVG} \leq$ 10 A			**12.5**	A
Output power (average)	P_{OUT_AVG}	$I_{OUT_AVG} \leq$ 10 A			**135**	W
Efficiency (ambient)	η_{AMB}	V_{IN} = 48 V, I_{OUT} = 10 A	93.5	94.7		%
		V_{IN} = 26 V to 55 V, I_{OUT} = 10 A	90.0			
		V_{IN} = 48 V, I_{OUT} = 5 A	94.0	94.9		
Efficiency (hot)	η_{HOT}	V_{IN} = 48 V, T_C = 100°C, I_{OUT} = 10 A	92.6	94.1		%
Efficiency (Over load range)	$\eta_{20\%}$	2 A < I_{OUT} < 10 A	**72.0**			%
Output resistance (Cold)	R_{OUT_COLD}	T_C = -40°C, I_{OUT} = 10 A	20.0	26.9	40.0	mΩ
Output resistance (Ambient)	R_{OUT_AMB}	T_C = 25°C, I_{OUT} = 10 A	25	38.3	50.0	mΩ
Output resistance (Hot)	R_{OUT_HOT}	T_C = 100°C, I_{OUT} = 10 A	30.0	47.1	60.0	mΩ
Switching frequency	F_{SW}		**1.40**	1.50	**1.60**	MHz
Output ripple frequency	F_{SW_RP}		**2.80**	3.00	**3.20**	MHz
Output voltage ripple	V_{OUT_PP}	C_{OUT} = 0 F, I_{OUT} = 10 A, V_{IN} = 48 V, 20 MHz BW, Section 12		200	**400**	mV
Output inductance (parasitic)	L_{OUT_PAR}	Frequency up to 30 MHz, Simulated J-lead model		600		pH
Output capacitance (internal)	C_{OUT_INT}	V_{OUT} = 12 V		20		µF
Output capacitance (external)	C_{OUT_EXT}	VTM Standalone Operation V_{IN} pre-applied, VC enable			**500**	µF
PROTECTION						
OVLO	V_{IN_OVLO+}	Module latched shutdown	**55.1**	58.7	**60**	V
Overvoltage lockout response time	T_{OVLO}	Effective internal RC filter		2.4		µs
Output overcurrent trip	I_{OCP}		**12**	19	**24**	A
Short circuit protection trip current	I_{SCP}		24			A
Output overcurrent response time constant	T_{OCP}	Effective internal RC filter (Integrative).		5.3		ms
Short circuit protection response time	T_{SCP}	From detection to cessation of switching (Instantaneous)		1		µs
Thermal shutdown setpoint	T_{J_OTP}		125	130	135	°C

3.0 SIGNAL CHARACTERISTICS

Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of **-40°C < T_J < 125°C (T-Grade)**; All other specifications are at **T_J = 25°C** unless otherwise noted.

VTM CONTROL : VC

- Used to wake up powertrain circuit.
- A minimum of 11.5 V must be applied indefinitely for V_{IN} < 26 V to ensure normal operation.
- VC slew rate must be within range for a successful start.
- PRM™ VC can be used as valid wake-up signal source.
- VC voltage may be continuously applied; there will be minimal VC current drawn when V_{IN} > 26 V and VC < 12.
- Internal resistance used in adaptive loop compensation

SIGNAL TYPE	STATE	ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
ANALOG INPUT	Steady	External VC voltage	V_{VC_EXT}	Required for startup, and operation below 26 V. See Section 7.	**11.5**		**16.5**	V
		VC current draw threshold	V_{VC_TH}	Low VC current draw for V_{IN} >26 V		12		V
		VC current draw	I_{VC}	VC = 12 V, V_{IN} = 0 V		71	**150**	mA
				VC = 12 V, V_{IN} > 26 V		21		
				VC = 16.5 V, V_{IN} > 26 V		75		
		VC internal resistor	R_{VC-INT}			2.05		kΩ
	Start Up	VC slew rate	dVC/dt	Required for proper startup;	**0.02**		**0.25**	V/µs
		VC inrush current	I_{INR_VC}	VC = 16.5 V, dVC/dt = 0.25 V/µs			**750**	mA
	Transitional	VC output turn-on delay	T_{ON}	V_{IN} pre-applied, PC floating, VC enable C_{PC} = 0 µF, C_{OUT} = 500 µF			**500**	µs
		VC to PC delay	T_{VC_PC}	VC = 11.5 V to PC high, V_{IN} = 0 V, dVC/dt = 0.25 V/µs		10	**25**	µs
		Internal VC capacitance	C_{VC_INT}	VC = 0 V		2.2		µF

PRIMARY CONTROL : PC

- The PC pin enables and disables the VTM. When held below 2 V, the VTM will be disabled.
- PC pin outputs 5 V during normal operation. PC pin is equal to 2.5 V during fault mode given V_{IN} > 26 V and VC > 11.5 V.
- After successful start-up and under no fault condition, PC can be used as a 5 V regulated voltage source with a 2 mA maximum current.
- Module will shutdown when pulled low with an impedance less than 400 Ω.
- In an array of VTMs, connect PC pin to synchronize startup.
- PC pin cannot sink current and will not disable other module during fault mode.

SIGNAL TYPE	STATE	ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
ANALOG OUTPUT	Steady	PC voltage	V_{PC}		**4.7**	5.0	**5.3**	V
		PC source current	I_{PC_OP}				2	mA
		PC resistance (internal)	R_{PC_INT}	Internal pull down resistor	**50**	150	**400**	kΩ
	Start Up	PC source current	I_{PC_EN}		**50**	100	**300**	µA
		PC capacitance (internal)	C_{PC_INT}	Section 7			**588**	pF
		PC resistance (external)	R_{PC_EXT}		**60**			kΩ
DIGITAL INPUT / OUTPUT	Enable	PC voltage (enable)	V_{PC_EN}		**2**	2.5	**3**	V
	Disable	PC voltage (disable)	V_{PC_DIS}				**2**	V
		PC pull down current	I_{PC_PD}		**5.1**			mA
	Transitional	PC disable time	$T_{PC_DIS_T}$			4		µs
		PC fault response time	T_{FR_PC}	From fault to PC = 2 V		100		µs

TEMPERATURE MONITOR : TM

- The TM pin monitors the internal temperature of the VTM controller IC within an accuracy of ±5°C.
- Can be used as a "Power Good" flag to verify that the VTM is operating.
- The TM pin has a room temperature setpoint of 3 V (@27°C) and approximate gain of 10 mV/ °C.

SIGNAL TYPE	STATE	ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
ANALOG OUTPUT	Steady	TM voltage	V_{TM_AMB}	T_J controller = 27°C	2.95	3.00	3.05	V
		TM source current	I_{TM}				**100**	µA
		TM gain	A_{TM}			10		mV/°C
		TM voltage ripple	V_{TM_PP}	C_{TM} = 0 F, V_{IN} = 48 V, I_{OUT} = 10 A		120	**200**	mV
DIGITAL OUTPUT (FAULT FLAG)	Disable	TM voltage	V_{TM_DIS}			0		V
	Transitional	TM resistance (internal)	R_{TM_INT}	Internal pull down resistor	**25**	40	**50**	kΩ
		TM capacitance (external)	C_{TM_EXT}				**50**	pF
		TM fault response time	T_{FR_TM}	From fault to TM = 1.5 V		10		µs

3.0 SIGNAL CHARACTERISTICS (CONT.)

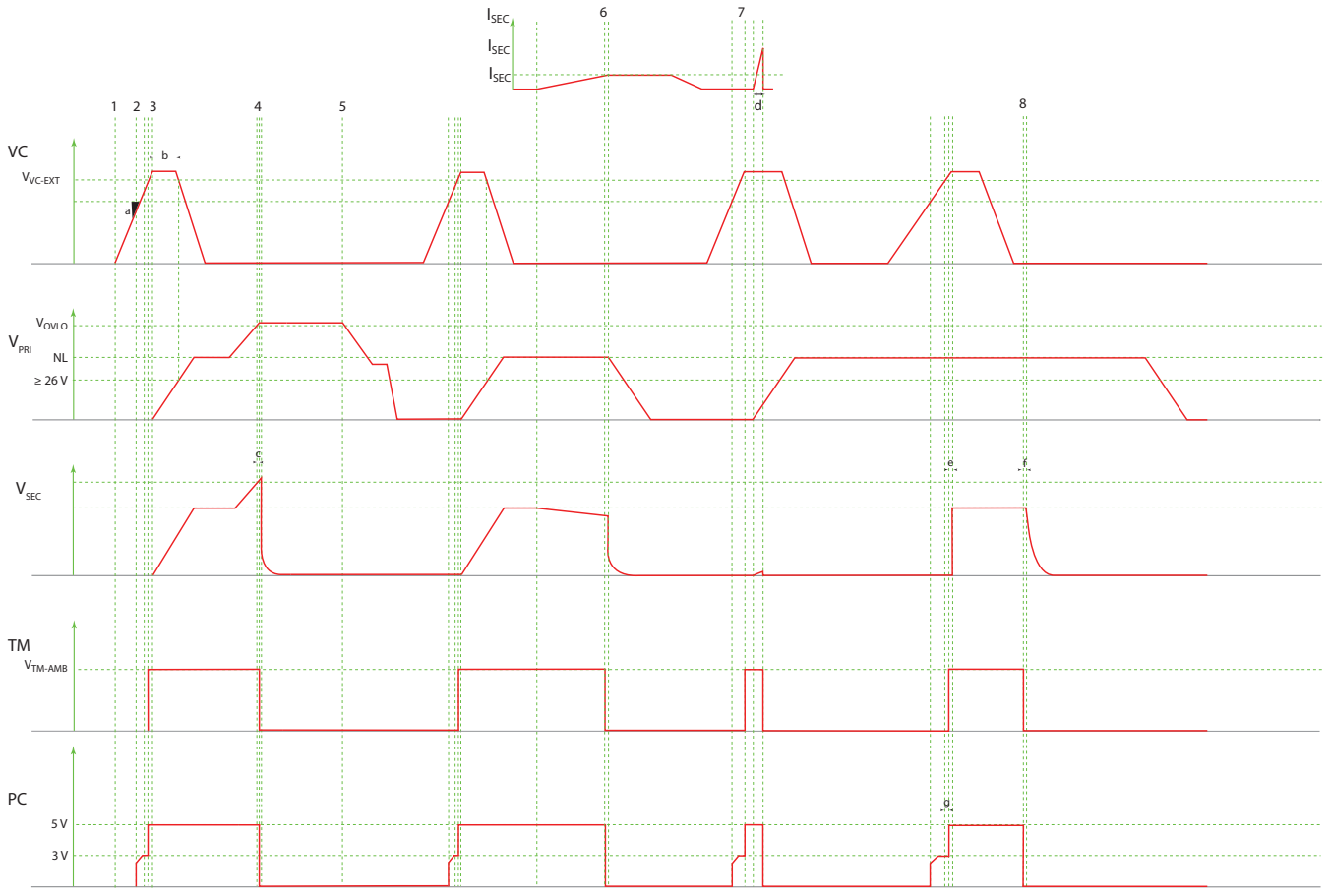
Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of **-40°C < T_J < 125°C (T-Grade)**; All other specifications are at **T_J = 25°C** unless otherwise noted.

CURRENT MONITOR : IM

- The nominal IM pin voltage varies between 0.38 V and 2.03 V representing the output current within ±25% under all operating line temperature conditions between 50% and 100%.
- The IM pin provides a DC analog voltage proportional to the output current of the VTM.

SIGNAL TYPE	STATE	ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
ANALOG OUTPUT	Steady	IM voltage (no load)	V_{IM_NL}	T_C = 25°C, V_{IN} = 48 V, I_{OUT} = 0 A	0.06	0.38	0.5	V
		IM voltage (50%)	$V_{IM_50\%}$	T_C = 25°C, V_{IN} = 48 V, I_{OUT} = 5 A		1.17		V
		IM voltage (full load)	V_{IM_FL}	T_C = 25°C, V_{IN} = 48 V, I_{OUT} = 10 A		2.03		V
		IM gain	A_{IM}	T_C = 25°C, V_{IN} = 48 V, I_{OUT} > 5 A		172		mV/A
		IM resistance (external)	R_{IM_EXT}		**2.5**			MΩ

4.0 TIMING DIAGRAM



a: VC slew rate (dVC/dt)
b: Minimum VC pulse rate
c: T_{OVLO_PIN}
d: T_{OCP_SEC}
e: Secondary turn on delay (T_{ON})
f: PC disable time ($T_{PC_DIS_T}$)
g: VC to PC delay (T_{VC_PC})

1. Initiated VC pulse
2. Controller start
3. V_{PRI} ramp up
4. V_{PRI} = VOVLO
5. V_{PRI} ramp down no VC pulse
6. Overcurrent, Secondary
7. Start up on short circuit
8. PC driven low

Notes:
– Timing and voltage is not to scale
– Error pulse width is load dependent

5.0 APPLICATION CHARACTERISTICS

The following values, typical of an application environment, are collected at T_C = 25ºC unless otherwise noted. See associated figures for general trend data.

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	TYP	UNIT
No load power dissipation	P_{NL}	V_{IN} = 48 V	2.1	W
Efficiency (ambient)	η_{AMB}	V_{IN} = 48 V, I_{OUT} = 10 A	94.5	%
Efficiency (hot)	η_{HOT}	V_{IN} = 48 V, I_{OUT} = 10 A, T_C = 100ºC	94.0	%
Output resistance (ambient)	R_{OUT_AMB}	V_{IN} = 48 V, I_{OUT} = 10 A	50.1	mΩ
Output resistance (hot)	R_{OUT_HOT}	V_{IN} = 48 V, I_{OUT} = 10 A, T_C = 100ºC	57.4	mΩ
Output resistance (cold)	R_{OUT_COLD}	V_{IN} = 48 V, I_{OUT} = 10 A, T_C = -40ºC	40.7	mΩ
Output voltage ripple	V_{OUT_PP}	C_{OUT} = 0 F, I_{OUT} = 10 A, V_{IN} = 48 V, 20 MHz BW, Section 12	261	mV
V_{OUT} Transient (positive)	V_{OUT_TRAN+}	I_{OUT_STEP} = 0 A TO 10A, V_{IN} = 48 V, I_{SLEW} > 10 A/us	100	mV
V_{OUT} Transient (negative)	V_{OUT_TRAN-}	I_{OUT_STEP} = 10 A to 0 A, V_{IN} = 48 V I_{SLEW} > 10 A/us	100	mV

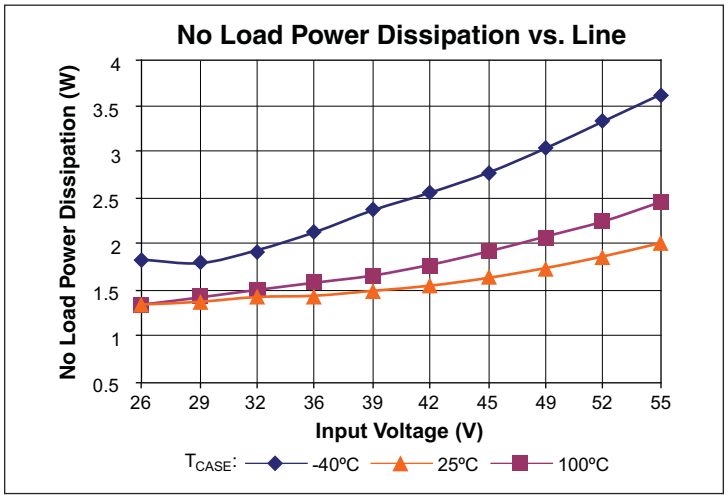


Figure 1 — *No load power dissipation vs. V_{IN}*

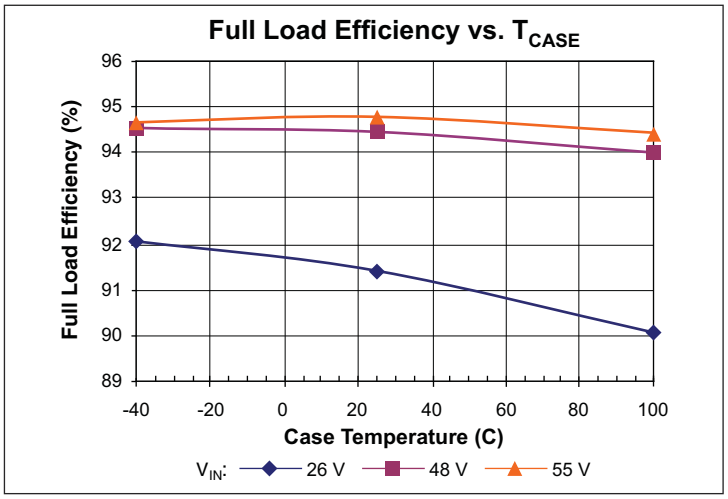


Figure 2 — *Full load efficiency vs. temperature*

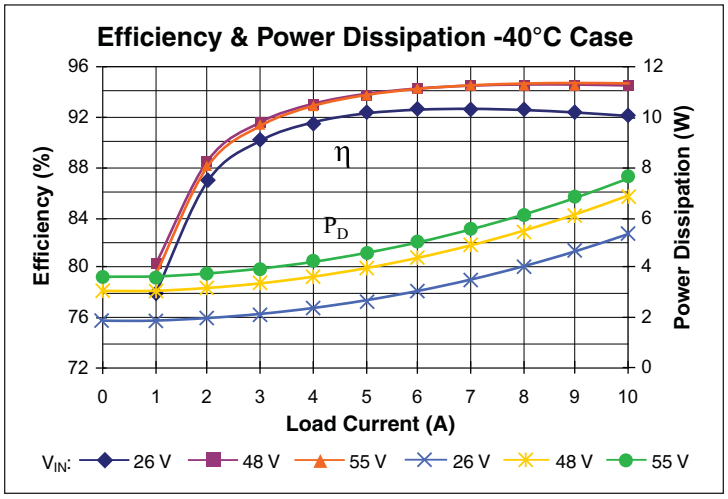


Figure 3 — *Efficiency and power dissipation at –40°C*

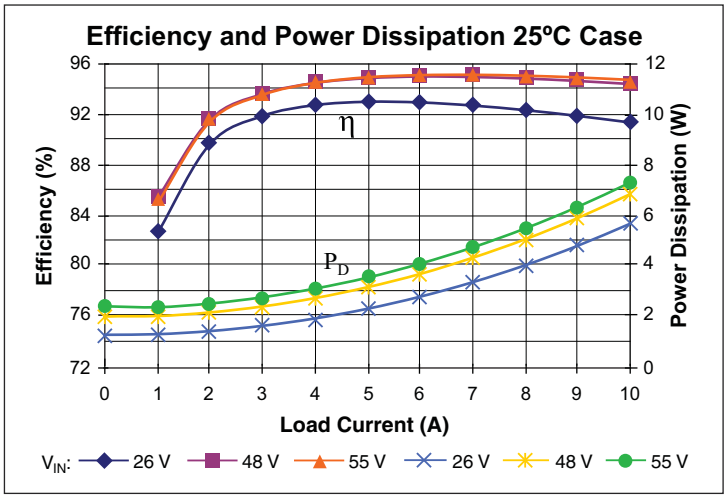


Figure 4 — *Efficiency and power dissipation at 25°C*

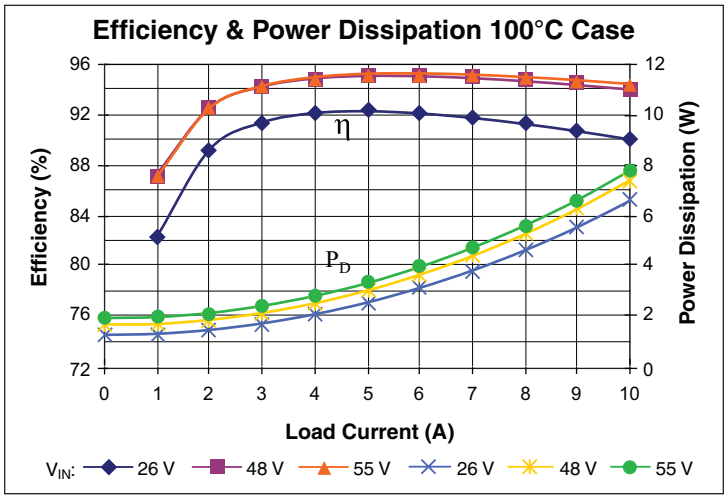


Figure 5 — *Efficiency and power dissipation at 100°C*

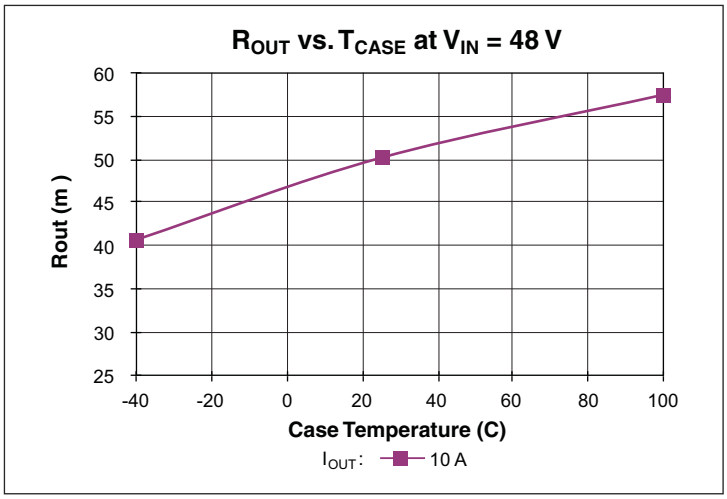


Figure 6 — *R_{OUT} vs. temperature*

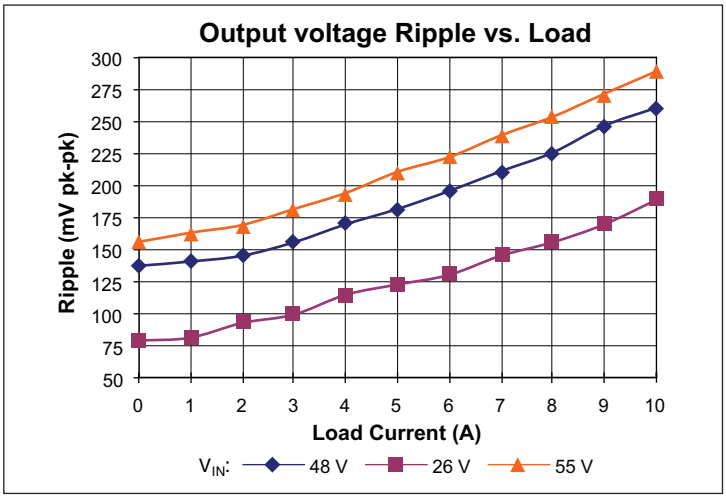


Figure 7 — *V_{RIPPLE} vs. I_{OUT}; No external C_{OUT}. Board mounted module, scope setting: 20 MHz analog BW*

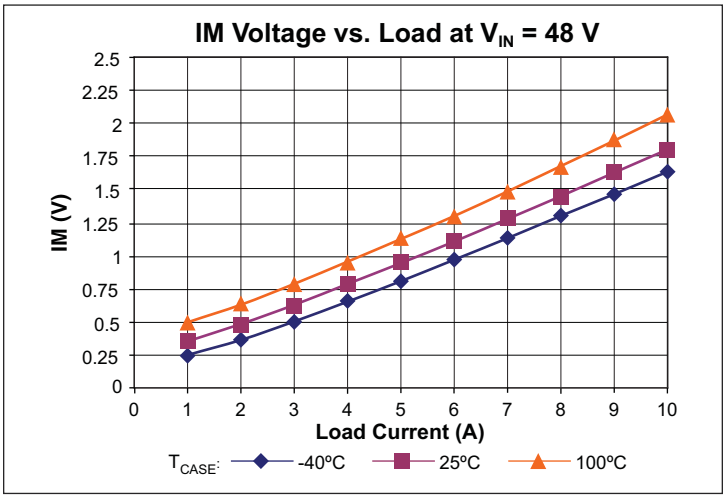


Figure 8 — *IM voltage vs. load*

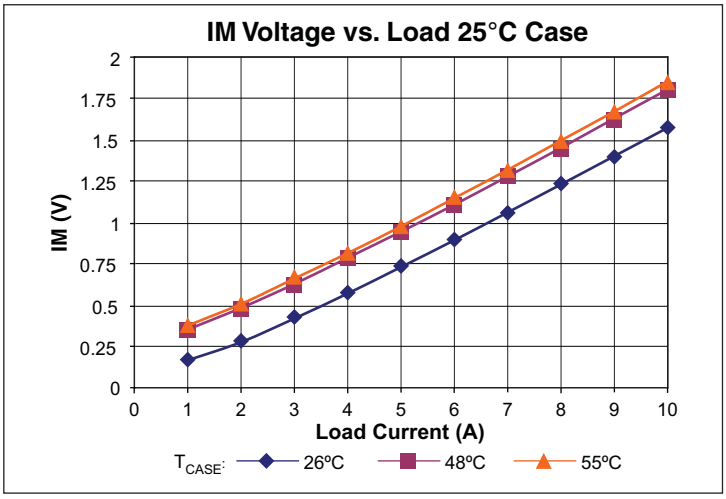


Figure 9 — *IM voltage vs. load*

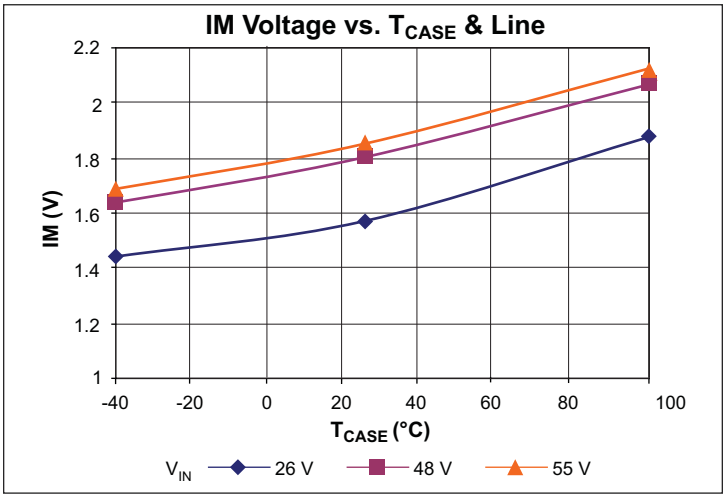


Figure 10 — *Full load IM voltage vs. T_{CASE}*

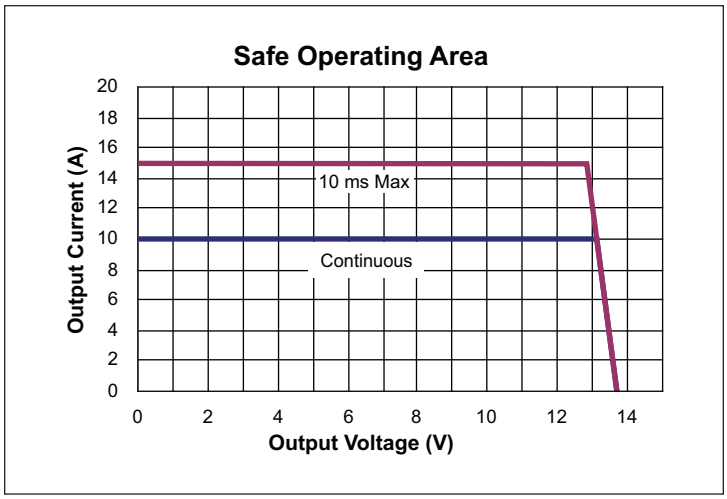


Figure 11 — *Safe operating area*

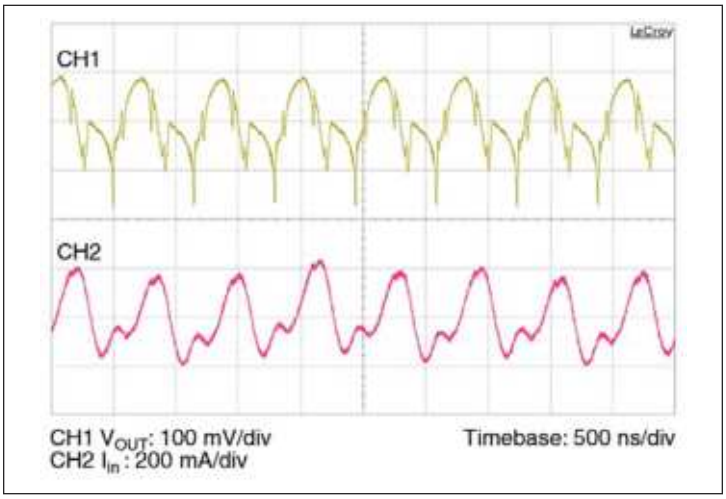


Figure 12 — *Full load ripple, 100 µF C_{IN}; No external C_{OUT}. Board mounted module, scope setting : 20 MHz analog BW*

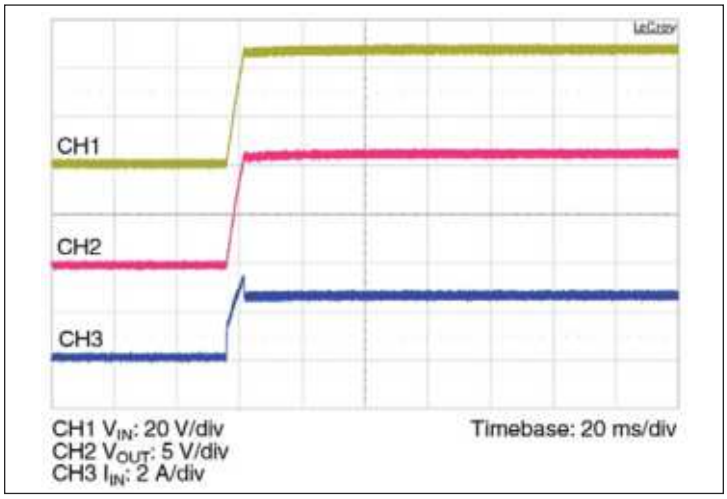


Figure 13 — *Start up from application of V_{IN} ; VC pre-applied C_{OUT} = 500 µF*

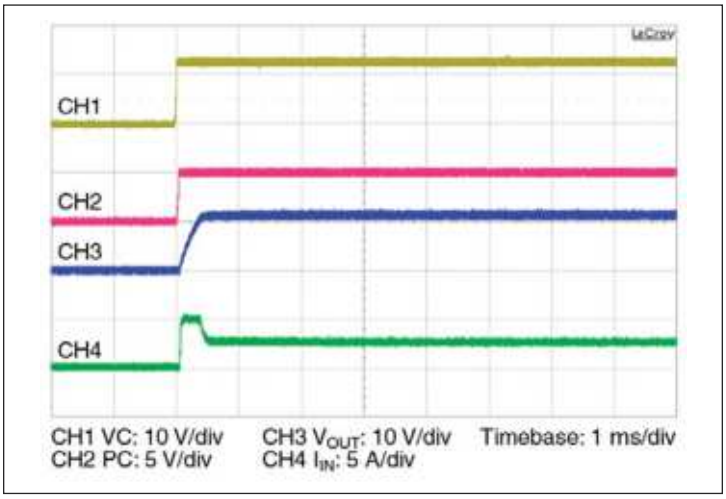


Figure 14 — *Start up from application of VC; V_{IN} pre-applied C_{OUT} = 500 µF*

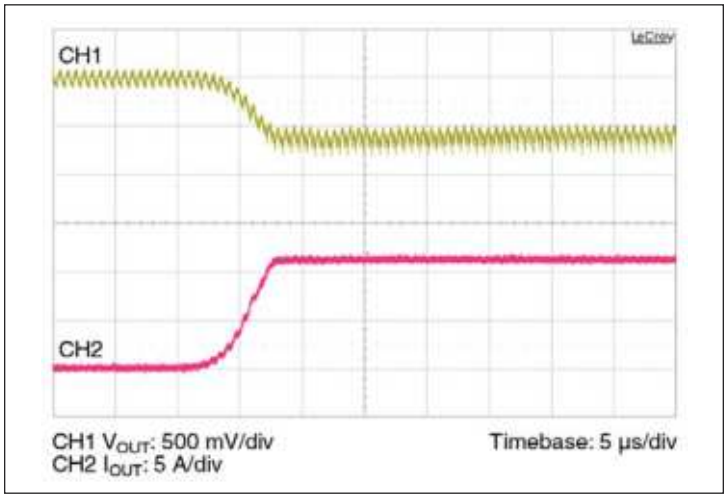


Figure 15 — *0 A – 10 A transient response: C_{IN} = 100 µF, no external C_{OUT}*

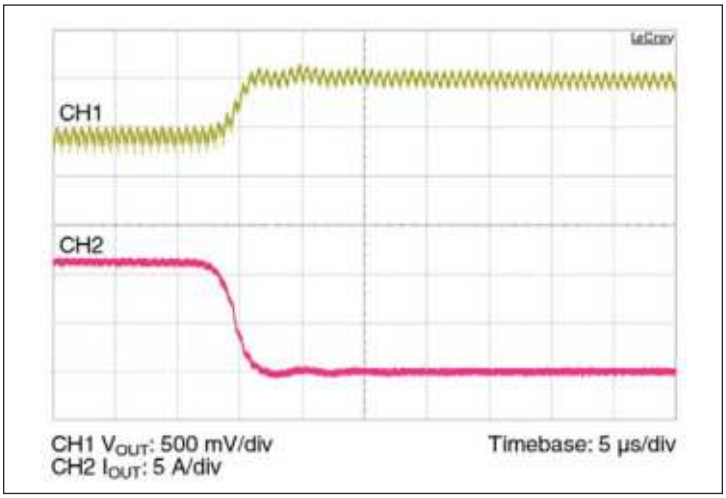


Figure 16 — *10 A – 0 A transient response: C_{IN} = 100 µF, no external C_{OUT}*

6.0 GENERAL CHARACTERISTICS

Specifications apply over all line and load conditions unless otherwise noted; **Boldface** specifications apply over the temperature range of **-40°C < T_J < 125°C (T-Grade)**; All Other specifications are at **T_J = 25°C** unless otherwise noted.

ATTRIBUTE	SYMBOL	CONDITIONS / NOTES	MIN	TYP	MAX	UNIT
MECHANICAL						
Length	L		21.7 / [0.85]	22.0 / [0.87]	22.3 / [0.88]	mm/[in]
Width	W		16.4 / [0.64]	16.5 / [0.65]	16.6 / [0.66]	mm/[in]
Height	H		6.48 / [0.255]	6.73 / [0.265]	6.98 / [0.275]	mm/[in]
Volume	Vol	No heat sink		2.44 / [0.150]		cm^3/[in^3]
Weight	W			8.0 / 0.28		g/[oz]
Lead finish		Nickel	0.51		2.03	µm
		Palladium	0.02		0.15	
		Gold	0.003		0.051	
THERMAL						
Operating temperature	T_J	VTM48EH120T010B00 (T-Grade)	-40		125	°C
		VTM48EH120M010B00 (M-Grade)	-55		125	°C
Thermal capacity				5		Ws/°C
ASSEMBLY						
Peak compressive force Applied to case (Z-axis)		Supported by J-lead only		2.5	3	lbs
Storage temperature	T_{ST}	VTM48EH120T010B00 (T-Grade)	-40		125	°C
		VTM48EH120M010B00 (M-Grade)	-65		125	°C
ESD withstand	ESD_{HBM}	Human Body Model, "JEDEC JESD 22-A114C.01"	1500			V_{DC}
	ESD_{MM}	Machine Model, "JEDEC JESD 22-A115-A"	400			
SOLDERING						
Peak temperature during reflow		RoHS			245	°C
		Non-RoHS			225	
Peak time above Liquidus		Requires AN:009 compliance	60		90	s
Peak heating rate during reflow		Requires AN:009 compliance	1	1.5	3	°C/s
Peak cooling rate post reflow		Requires AN:009 compliance	1	1.5	6	°C/s
SAFETY						
Isolation voltage (hipot)	V_{HIPOT}		**2250**			V_{DC}
Isolation capacitance	C_{IN_OUT}	Unpowered Unit	**1350**	1750	**2150**	pF
Isolation resistance	R_{IN_OUT}		**10**			MΩ
MTBF		MIL HDBK 217, 25°C, Ground Benign		5.0		MHrs
Agency approvals/standards		cTÜVus				
		cURus				
		CE Marked for low voltage directive and RoHS recast directive, as applicable				

7.0 USING THE CONTROL SIGNALS VC, PC, TM, IM

The VTM Control (VC) pin is an input pin which powers the internal VCC circuitry when within the specified voltage range of 11.5 V to 16.5 V. This voltage is required in order for the VTM module to start, and must be applied as long as the input is below 26 V. In order to ensure a proper start, the slew rate of the applied voltage must be within the specified range.

Some additional notes on the using the VC pin:

- In most applications, the VTM module will be powered by an upstream PRM™ which provides a 10 ms VC pulse during startup. In these applications the VC pins of the PRM and VTM should be tied together.
- The VC voltage can be applied indefinitely allowing for continuous operation down to 0 V_{IN}.
- The fault response of the VTM module is latching. A positive edge on VC is required in order to restart the unit. If VC is continuously applied the PC pin may be toggled to restart the module.

Primary Control (PC) pin can be used to accomplish the following functions:

- Delayed start: Upon the application of VC, the PC pin will source a constant 100 µA current to the internal RC network. Adding an external capacitor will allow further delay in reaching the 2.5 V threshold for module start.
- Auxiliary voltage source: Once enabled in regular operational conditions (no fault), each VTM PC provides a regulated 5 V, 2 mA voltage source.
- Output disable: PC pin can be actively pulled down in order to disable the module. Pull down impedance shall be lower than 400 Ω.
- Fault detection flag: The PC 5 V voltage source is internally turned off as soon as a fault is detected. It is important to notice that PC doesn't have current sink capability. Therefore, in an array, PC line will not be capable of disabling neighboring modules if a fault is detected.
- Fault reset: PC may be toggled to restart the unit if VC is continuously applied.

Temperature Monitor (TM) pin provides a voltage proportional to the absolute temperature of the converter control IC.

It can be used to accomplish the following functions:

- Monitor the control IC temperature: The temperature in Kelvin is equal to the voltage on the TM pin scaled by 100. (i.e. 3.0 V = 300 K = 27°C). If a heat sink is applied, TM can be used to thermally protect the system.
- Fault detection flag: The TM voltage source is internally turned off as soon as a fault is detected. For system monitoring purposes (microcontroller interface) faults are detected on falling edges of TM signal.

Current Monitor (IM) pin provides a voltage proportional to the output current of the VTM module. The nominal voltage will vary between 0.38 V and 2.03 V over the output current range of the module (See Figures 8–10). The accuracy of the IM pin will be within 25% under all line and temperature conditions between 50% and 100% load.

8.0 STARTUP BEHAVIOR

Depending on the sequencing of the VC with respect to the input voltage, the behavior during startup will vary as follows:

- Normal Operation (VC applied prior to V_{IN}): In this case the controller is active prior to ramping the input. When the input voltage is applied, the VTM output voltage will track the input (See Figure 13). The inrush current is determined by the input voltage rate of rise and output capacitance. If the VC voltage is removed prior to the input reaching 26 V, the VTM module may shut down.
- Stand Alone Operation (VC applied after V_{IN}): In this case the module output will begin to rise upon the application of the VC voltage (See Figure 14). The Adaptive Soft Start circuit (See Section 10) may vary the ouput rate of rise in order to limit the inrush current to it's maximum level. When starting into high capacitance, or a short, the output current will be limited for a maximum of 900 µsec. After this period, the adaptive soft start circuit will time out and the module may shut down. No restart will be attempted until VC is re-applied, or PC is toggled. The maximum output capacitance is limited to 500 µF in this mode of operation to ensure a sucessful start.

9.0 THERMAL CONSIDERATIONS

VI Chip® products are multi-chip modules whose temperature distribution varies greatly for each part number as well as with the input / output conditions, thermal management and environmental conditions. Maintaining the top of the VTM48EH120T010B00 case to less than 100°C will keep all junctions within the VI Chip below 125°C for most applications.

The percent of total heat dissipated through the top surface versus through the J-lead is entirely dependent on the particular mechanical and thermal environment. The heat dissipated through the top surface is typically 60%. The heat dissipated through the J-lead onto the PCB board surface is typically 40%. Use 100% top surface dissipation when designing for a conservative cooling solution.

It is not recommended to use a VI Chip module for an extended period of time at full load without proper heat sinking.

11.0 SINE AMPLITUDE CONVERTER™ POINT OF LOAD CONVERSION

The Sine Amplitude Converter (SAC™) uses a high frequency resonant tank to move energy from input to output. (The resonant tank is formed by Cr and leakage inductance Lr in the power transformer windings as shown in the VTM™ Module Block Diagram. See Section 10). The resonant LC tank, operated at high frequency, is amplitude modulated as function of input voltage and output current. A small amount of capacitance embedded in the input and output stages of the module is sufficient for full functionality and is key to achieving power density.

The VTM48EH120T010B00 SAC can be simplified into the following model:

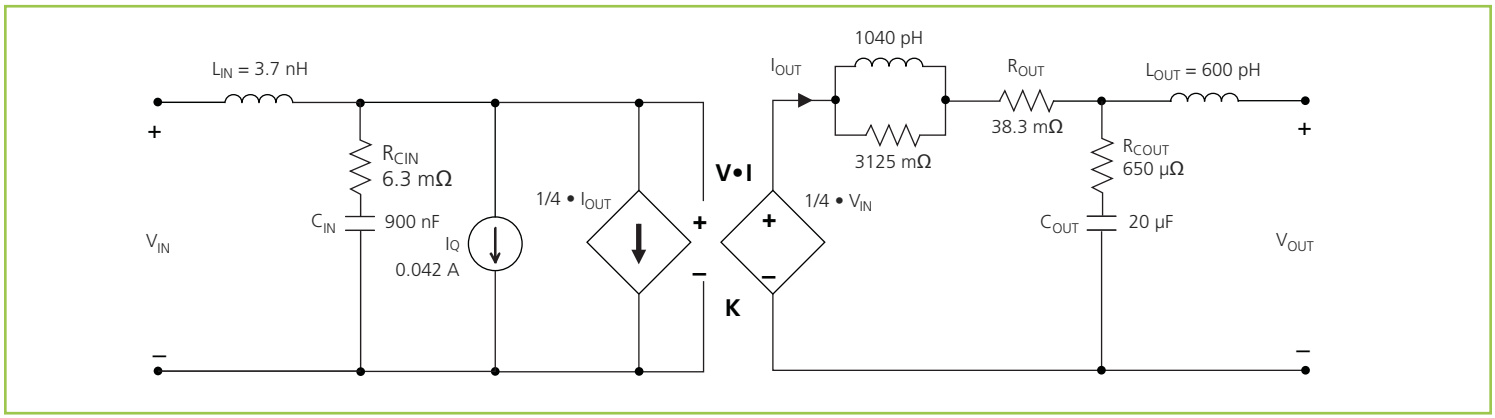


Figure 17 — *VI Chip® module AC model*

At no load:

$$V_{OUT} = V_{IN} \bullet K \quad (1)$$

K represents the "turns ratio" of the SAC. Rearranging Eq (1):

$$K = \frac{V_{OUT}}{V_{IN}} \quad (2)$$

In the presence of load, V_{OUT} is represented by:

$$V_{OUT} = V_{IN} \bullet K - I_{OUT} \bullet R_{OUT} \quad (3)$$

and I_{OUT} is represented by:

$$I_{OUT} = \frac{I_{IN} - I_Q}{K} \quad (4)$$

R_{OUT} represents the impedance of the SAC, and is a function of the R_{DSON} of the input and output MOSFETs and the winding resistance of the power transformer. I_Q represents the quiescent current of the SAC control and gate drive circuitry.

The use of DC voltage transformation provides additional interesting attributes. Assuming for the moment that R_{OUT} = 0 Ω and I_Q = 0 A, Eq. (3) now becomes Eq. (1) and is essentially load independent. A resistor R is now placed in series with V_{IN} as shown in Figure 18.

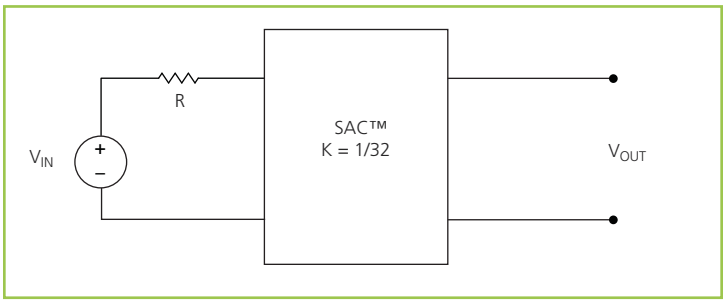


Figure 18 — *K = 1/32 Sine Amplitude Converter™ with series input resistor*

The relationship between V_{IN} and V_{OUT} becomes:

$$V_{OUT} = (V_{IN} - I_{IN} \bullet R) \bullet K \quad (5)$$

Substituting the simplified version of Eq. (4) (I_Q is assumed = 0 A) into Eq. (5) yields:

$$V_{OUT} = V_{IN} \bullet K - I_{OUT} \bullet R \bullet K^2 \quad (6)$$

This is similar in form to Eq. (3), where R_{OUT} is used to represent the characteristic impedance of the SAC™. However, in this case a real R on the input side of the SAC is effectively scaled by K^2 with respect to the output.

Assuming that R = 1 Ω, the effective R as seen from the secondary side is 0.98 mΩ, with K = 1/32 as shown in Figure 18.

A similar exercise should be performed with the additon of a capacitor, or shunt impedance, at the input to the SAC. A switch in series with V_{IN} is added to the circuit. This is depicted in Figure 19.

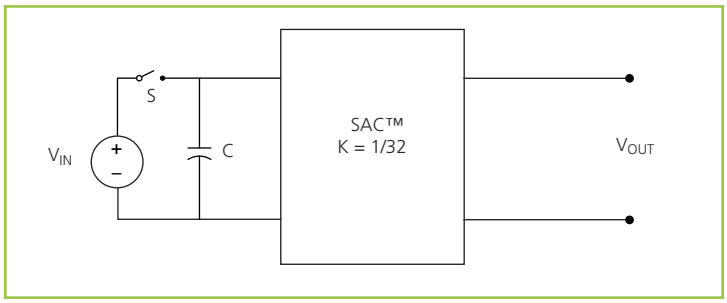


Figure 19 — *Sine Amplitude Converter™ with input capacitor*

A change in V_{IN} with the switch closed would result in a change in capacitor current according to the following equation:

$$I_C(t) = C\frac{dV_{IN}}{dt} \quad (7)$$

Assume that with the capacitor charged to V_{IN}, the switch is opened and the capacitor is discharged through the idealized SAC. In this case,

$$I_C = I_{OUT} \bullet K \quad (8)$$

Substituting Eq. (1) and (8) into Eq. (7) reveals:

$$I_{OUT} = \frac{C}{K^2} \bullet \frac{dV_{OUT}}{dt} \quad (9)$$

Writing the equation in terms of the output has yielded a K^2 scaling factor for C, this time in the denominator of the equation. For a K factor less than unity, this results in an effectively larger capacitance on the output when expressed in terms of the input. With a K = 1/32 as shown in Figure 19, C = 1 µF would effectively appear as C = 1024 µF when viewed from the output.

Low impedance is a key requirement for powering a high-current, low-voltage load efficiently. A switching regulation stage should have minimal impedance, while simultaneously providing appropriate filtering for any switched current. The use of a SAC between the regulation stage and the point of load provides a dual benefit, scaling down series impedance leading back to the source and scaling up shunt capacitance (or energy storage) as a function of its K factor squared. However, these benefits are not useful if the series impedance of the SAC is too high. The impedance of the SAC must be low well beyond the crossover frequency of the system.

A solution for keeping the impedance of the SAC low involves switching at a high frequency. This enables magnetic components to be small since magnetizing currents remain low. Small magnetics mean small path lengths for turns. Use of low loss core material at high frequencies reduces core losses as well.

The two main terms of power loss in the VTM™ module are:

- No load power dissipation (P_{NL}): defined as the power used to power up the module with an enabled power train at no load.
- Resistive loss (R_{OUT}): refers to the power loss across the VTM current multiplier modeled as pure resistive impedance.

$$P_{DISSIPATED} = P_{NL} + P_{R_{OUT}} \quad (10)$$

Therefore,

$$P_{OUT} = P_{IN} - P_{DISSIPATED} = P_{IN} - P_{NL} - P_{R_{OUT}} \quad (11)$$

The above relations can be combined to calculate the overall module efficiency:

$$\eta = \frac{P_{OUT}}{P_{IN}} = \frac{P_{IN} - P_{NL} - P_{R_{OUT}}}{P_{IN}} \quad (12)$$

$$= \frac{V_{IN} \bullet I_{IN} - P_{NL} - (I_{OUT})^2 \bullet R_{OUT}}{V_{IN} \bullet I_{IN}}$$

$$= 1 - \left(\frac{P_{NL} + (I_{OUT})^2 \bullet R_{OUT}}{V_{IN} \bullet I_{IN}}\right)$$

12.0 INPUT AND OUTPUT FILTER DESIGN

A major advantage of a SAC™ system versus a conventional PWM converter is that the former does not require large functional filters. The resonant LC tank, operated at extreme high frequency, is amplitude modulated as a function of input voltage and output current and efficiently transfers charge through the isolation transformer. A small amount of capacitance embedded in the input and output stages of the module is sufficient for full functionality and is key to achieving high power density.

This paradigm shift requires system design to carefully evaluate external filters in order to:

1. Guarantee low source impedance.

   To take full advantage of the VTM module dynamic response, the impedance presented to its input terminals must be low from DC to approximately 5 MHz. Input capacitance may be added to improve transient performance or compensate for high source impedance.

2. Further reduce input and/or output voltage ripple without sacrificing dynamic response.

   Given the wide bandwidth of the VTM module, the source response is generally the limiting factor in the overall system response. Anomalies in the response of the source will appear at the output of the module multiplied by its K factor.

3. Protect the module from overvoltage transients imposed by the system that would exceed maximum ratings and cause failures.

   The VI Chip® module input/output voltage ranges must not be exceeded. An internal overvoltage lockout function prevents operation outside of the normal operating input range. Even during this condition, the powertrain is exposed to the applied voltage and power MOSFETs must withstand it.

13.0 CAPACITIVE FILTERING CONSIDERATIONS FOR A SINE AMPLITUDE CONVERTER

It is important to consider the impact of adding input and output capacitance to a Sine Amplitude Converter™ on the system as a whole. Both the capacitance value, and the effective impedance of the capacitor must be considered.

A Sine Amplitude Converter has a DC R_{OUT} value which has already been discussed in section 11. The AC R_{OUT} of the SAC contains several terms:

- Resonant tank impedance
- Input lead inductance and internal capacitance
- Output lead inductance and internal capacitance

The values of these terms are shown in the behavioral model in section 11. It is important to note on which side of the transformer these impedances appear and how they reflect across the transformer given the K factor.

The overall AC impedance varies from model to model but for most models it is dominated by DC R_{OUT} value from DC to beyond 500 KHz. The behavioral model in section 11 should be used to approximate the AC impedance of the specific model.

Any capacitors placed at the output of the VTM module reflect back to the input of the module by the square of the K factor (Eq. 9) with the impedance of the module appearing in series. It is very important to keep this in mind when using a PRM™ regulator to power the VTM. Most PRM™ regulators have a limit on the maximum amount of capacitance that can be applied to the output. This capacitance includes both the regulator output capacitance and the current multiplier output capacitance reflected back to the input. In PRM regulator remote sense applications, it is important to consider the reflected value of VTM current multiplier output capacitance when designing and compensating the PRM regulator control loop.

Capacitance placed at the input of the VTM module appear to the load reflected by the K factor, with the impedance of the VTM module in series. In step-down VTM ratios, the effective capacitance is increased by the K factor. The effective ESR of the capacitor is decreased by the square of the K factor, but the impedance of the VTM module appears in series. Still, in most step-down VTM modules an electrolytic capacitor placed at the input of the module will have a lower effective impedance compared to an electrolytic capacitor placed at the output. This is important to consider when placing capacitors at the output of the current multiplier. Even though the capacitor may be placed at the output, the majority of the AC current will be sourced from the lower impedance, which in most cases will be the VTM current multiplier. This should be studied carefully in any system design using a VTM current multiplier. In most cases, it should be clear that electrolytic output capacitors are not necessary to design a stable, well-bypassed system.

14.0 CURRENT SHARING

The SAC™ topology bases its performance on efficient transfer of energy through a transformer without the need of closed loop control. For this reason, the transfer characteristic can be approximated by an ideal transformer with some resistive drop and positive temperature coefficient.

This type of characteristic is close to the impedance characteristic of a DC power distribution system, both in behavior (AC dynamic) and absolute value (DC dynamic).

When connected in an array with the same K factor, the VTM module will inherently share the load current with parallel units, according to the equivalent impedance divider that the system implements from the power source to the point of load.

Some general recommendations to achieve matched array impedances:

- Dedicate common copper planes within the PCB to deliver and return the current to the modules.
- Provide the PCB layout as symmetric as possible.
- Apply same input / output filters (if present) to each unit.

For further details see AN:016 Using BCM® Bus Converters in High Power Arrays.

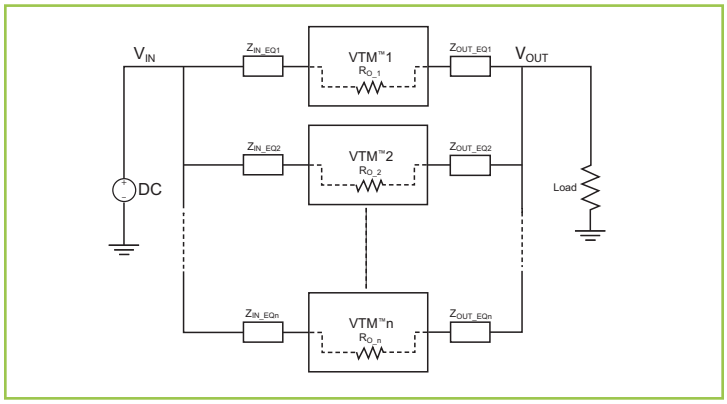


Figure 20 — *VTM module array*

15.0 FUSE SELECTION

In order to provide flexibility in configuring power systems VI Chip® products are not internally fused. Input line fusing of VI Chip products is recommended at system level to provide thermal protection in case of catastrophic failure.

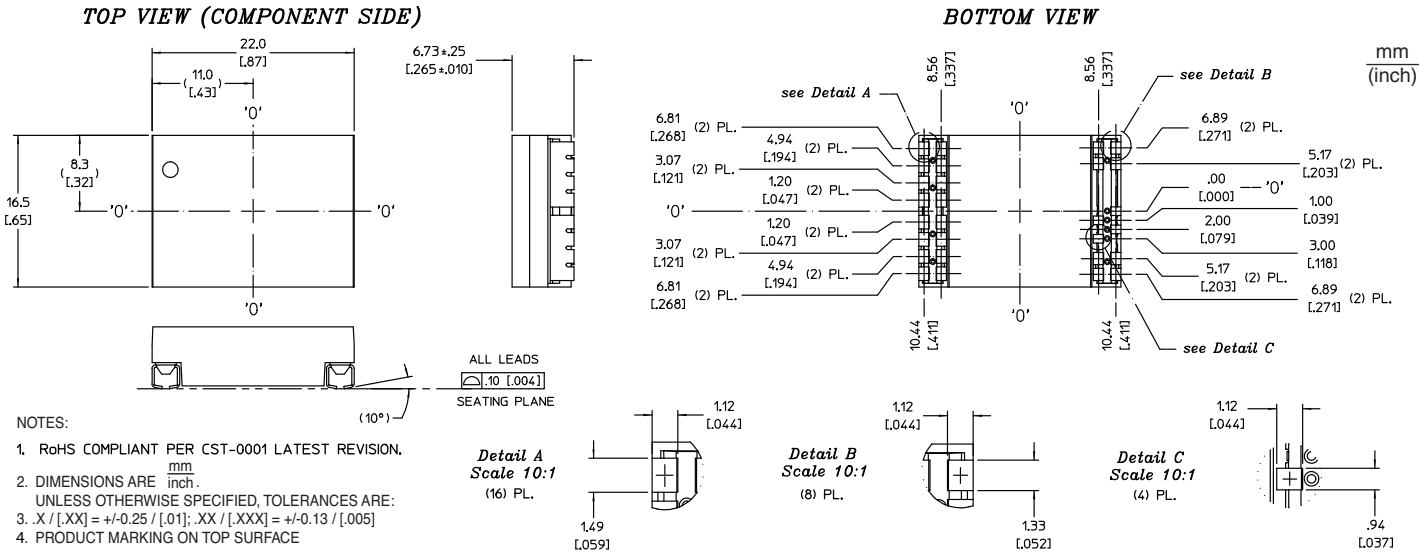
The fuse shall be selected by closely matching system requirements with the following characteristics:

- Current rating (usually greater than maximum VTM module current)
- Maximum voltage rating (usually greater than the maximum possible input voltage)
- Ambient temperature
- Nominal melting I^2t

16.0 REVERSE OPERATION

The VTM48EH120T010B00 is capable of reverse operation. If a voltage is present at the output which satisfies the condition $V_{OUT} > V_{IN} \bullet K$ at the time the VC voltage is applied, or after the unit has started, then energy will be transferred from secondary to primary. The input to output ratio will be maintained. The VTM48EH120T010B00 will continue to operate in reverse as long as the input and output are within the specified limits. The VTM48EH120T010B00 has not been qualified for continuous operation (>10 ms) in the reverse direction.

17.1 MECHANICAL DRAWING

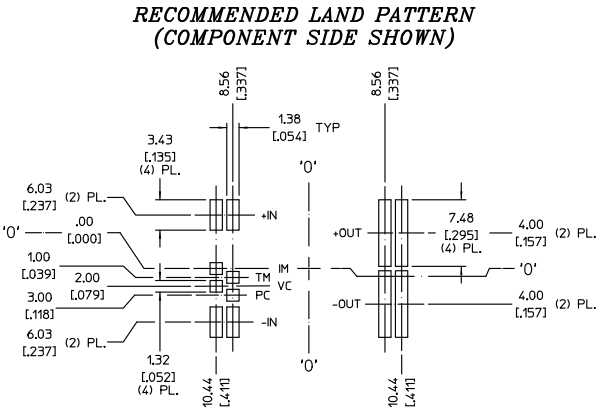


NOTES:

1. RoHS COMPLIANT PER CST-0001 LATEST REVISION.
2. DIMENSIONS ARE mm / inch.
   UNLESS OTHERWISE SPECIFIED, TOLERANCES ARE:
3. .X / [.XX] = +/-0.25 / [.01]; .XX / [.XXX] = +/-0.13 / [.005]
4. PRODUCT MARKING ON TOP SURFACE

DXF and PDF files are available on vicorpower.com

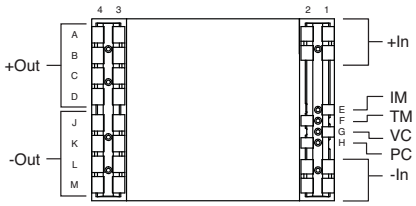
17.2 RECOMMENDED LAND PATTERN



NOTES:

1. RoHS COMPLIANT PER CST-0001 LATEST REVISION.
2. DIMENSIONS ARE mm / inch.
   UNLESS OTHERWISE SPECIFIED, TOLERANCES ARE:
3. .X / [.XX] = +/-0.25 / [.01]; .XX / [.XXX] = +/-0.13 / [.005]
4. PRODUCT MARKING ON TOP SURFACE

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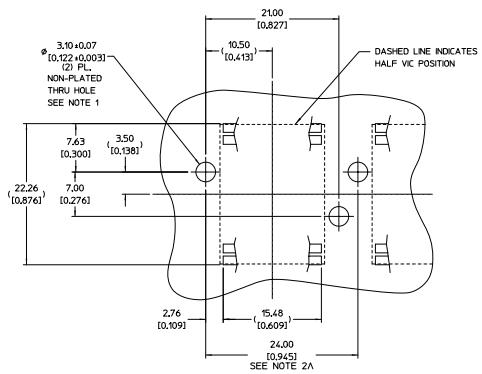
Bottom View

Signal Name	Designation
+In	A1-B1, A2-B2
–In	L1-M1, L2-M2
IM	E1
TM	F2
VC	G1
PC	H2
+Out	A3-D3, A4-D4
–Out	J3-M3, J4-M4

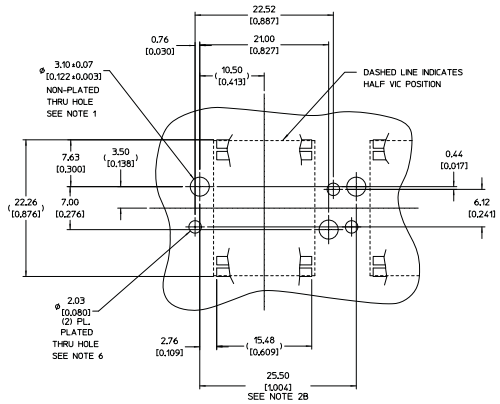
17.3 RECOMMENDED HEAT SINK PUSH PIN LOCATION

Notes:

1. Maintain 3.50 (0.138) Dia. keep-out zone free of copper, all PCB layers.
2. (A) minimum recommended pitch is 24.00 (0.945) this provides 7.50 (0.295) component edge–to–edge spacing, and 0.50 (0.020) clearance between Vicor heat sinks.
   (B) Minimum recommended pitch is 25.50 (1.004). This provides 9.00 (0.354) component edge–to–edge spacing, and 2.00 (0.079) clearance between Vicor heat sinks.
3. V•I Chip™ module land pattern shown for reference only, actual land pattern may differ. Dimensions from edges of land pattern to push–pin holes will be the same for all half size V•I Chip Products.
4. RoHS compliant per CST–0001 latest revision.
5. Unless otherwise specified:
   Dimensions are mm (inches)
   tolerances are:
   x.x (x.xx) = ±0.13 (0.01)
   x.xx (x.xxx) = ±0.13 (0.005)
6. Plated through holes for grounding clips (33855) shown for reference. Heat sink orientation and device pitch will dictate final grounding solution.



(NO GROUNDING CLIPS)



(WITH GROUNDING CLIPS)

Revision History

Revision	Date	Description	Page Number(s)
1.3	01/05/21	Provided additional information to soldering guidelines	10

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